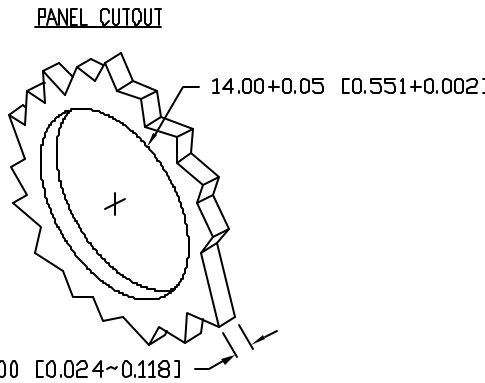
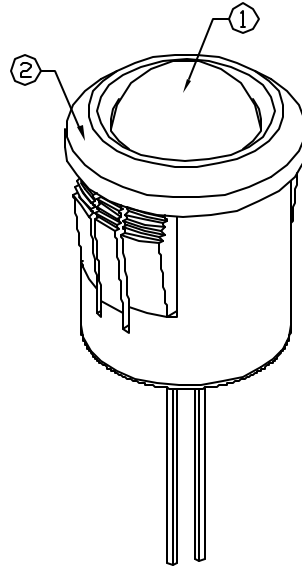
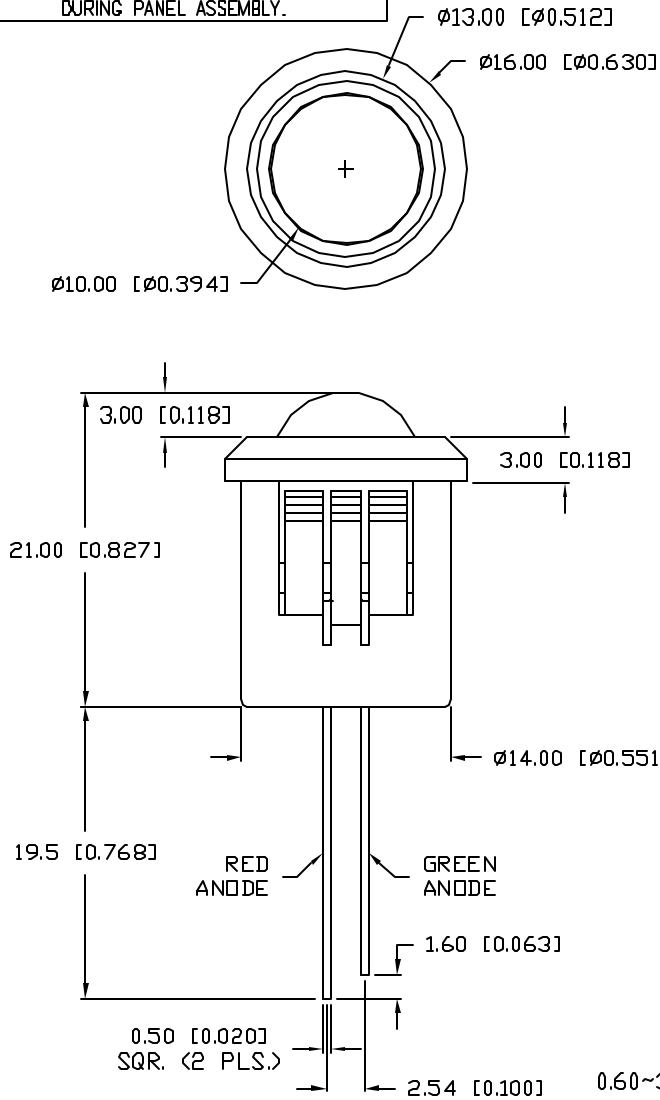


# UNCONTROLLED DOCUMENT

**CAUTION: PRESSURE SENSITIVE ASSEMBLY**  
 AVOID APPLYING PRESSURE TO LED  
 DURING PANEL ASSEMBLY.



PART NUMBER		REV.
SSI-LXH1090IGW		A
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10BRDR. & REDRAWN IN 3D.	1.5.02

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$					
PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		635 (RED)		nm	
		565 (GREEN)		nm	
FORWARD VOLTAGE (R/G)		2.0/2.2	2.5/2.6	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_f=100\mu\text{A}$
AXIAL INTENSITY (R/G)		30/25		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		60		2x theta	
EMITTED COLOR: RED/GREEN					
EPOXY LENS FINISH: MILKY WHITE DIFFUSED					

LIMITS OF SAFE OPERATION AT 25°C			
PARAMETER	COLORS	MAX	UNITS
PEAK FORWARD CURRENT*		150	mA
STEADY CURRENT	(R/G)	30/25	mA
POWER DISSIPATION		105	mW
DERATE FROM 25°C		-1.2	mW/°C
OPERATING, STORAGE TEMP.		-40 TO +85	°C
SOLDERING TEMP.		+260	°C
2.0mm FROM BODY			3 SEC. MAX


\*  $t < 10\mu\text{s}$

**NOTES:**

- SSL-LX100133IGW LED.
- SSH-RTF1090 HOLDER.
- UV EPOXY TO RETAIN LED IN HOLDER.

# UNCONTROLLED DOCUMENT

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN= <sup>+0.00</sup> <sub>-0.00</sub> DECIMAL PRECISION, MAX.= <sup>+0.00</sup> <sub>-0.00</sub> DECIMAL PRECISION

REV. A	PART NUMBER SSI-LXH1090IGW	CONFIDENTIAL INFORMATION THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC, THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.	 290 E. HELEN ROAD PALATINE, IL 60067-6976 PHONE: +1.847.359.2790 US WEB: www.lumex.com TW WEB: www.lumex.com.tw
T-10mm RED/GREEN LED PANEL INDICATOR, MILKY WHITE DIFFUSED LENS.		RELIABILITY NOTE OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.	DRAWN BY: BC CHECKED BY: APPROVED BY: DATE: 3.17.00 PAGE: 1 OF 1 SCALE: N/A